

ABSTRACT OF THE DISCLOSURE

A process solution applying apparatus comprising a substrate holding mechanism for holding a substrate, a process solution supplying system for applying process solution in a prescribed amount to the substrate held by the substrate holding mechanism, the process solution supplying system having a supplying mechanism for changing a rate at which the process solution is supplied, and a substrate rotating mechanism for rotating the substrate holding mechanism, thus rotating the substrate at a predetermined speed to spread the process solution by virtue of centrifugal force and to coat the substrate with the process solution.

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